



Product Change Notification / SYST-13AEAW012

Date:

18-Aug-2021

Product Category:

Memory

PCN Type:

Document Change

Notification Subject:

Data Sheet - 25LC512 Data Sheet Document Revision

Affected CPNs:

[SYST-13AEAW012_Affected_CPN_08182021.pdf](#)

[SYST-13AEAW012_Affected_CPN_08182021.csv](#)

Notification Text:

SYST-13AEAW012

Microchip has released a new Product Documents for the 25LC512 Data Sheet of devices. If you are using one of these devices please read the document located at [25LC512 Data Sheet](#).

Notification Status: Final

Description of Change:

- 1) Updated Pin Description section
- 2) Updated Package Drawings
- 3) Added Product Identification System for Automotive
- 4) Replaced terminology "Master" and "Slave" with "Host" and "Client", respectively
- 5) Reformatted some sections for better readability.

Impacts to Data Sheet: None

Reason for Change: To Improve Manufacturability

Change Implementation Status: Complete

Date Document Changes Effective: 18 Aug 2021

NOTE: Please be advised that this is a change to the document only the product has not been changed.

Markings to Distinguish Revised from Unrevised Devices: N/A

Attachments:

[25LC512 Data Sheet](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

25LC512-E/P
25LC512-I/P
25LC512-E/MF
25LC512-E/SN
25LC512-E/SN16KVAO
25LC512-E/SM
25LC512-E/SM16KVAO
25LC512-M/SN
25LC512-I/MF
25LC512-I/SN
25LC512-I/SN16KVAO
25LC512-I/SM
25LC512T-I/MF
25LC512T-I/SN
25LC512T-I/SN16KVAO
25LC512T-I/SM
25LC512T-M/SN
25LC512T-E/MF
25LC512T-E/SN
25LC512T-E/SN16KV01
25LC512T-E/SN16KVAO
25LC512T-E/SM
25LC512T-E/SM16KVAO

512 Kbit SPI Bus Serial EEPROM

Device Selection Table

Part Number	Vcc Range	Page Size	Temp. Ranges	Packages
25LC512	2.5-5.5V	128 Byte	I, E	P, SN, SM, MF

Features

- 20 MHz max. Clock Speed
- Byte and Page-level Write Operations:
 - 128-byte page
 - 5 ms max.
 - No page or sector erase required
- Low-Power CMOS Technology:
 - Max. Write Current: 5 mA at 5.5V, 20 MHz
 - Read Current: 10 mA at 5.5V, 20 MHz
 - Standby Current: 1µA at 2.5V (Deep power-down)
- Electronic Signature for Device ID
- Self-Timed Erase and Write cycles:
 - Page Erase (5 ms, typical)
 - Sector Erase (10 ms/sector, typical)
 - Bulk Erase (10 ms, typical)
- Sector Write Protection (16K byte/sector):
 - Protect none, 1/4, 1/2 or all of array
- Built-In Write Protection:
 - Power-on/off data protection circuitry
 - Write enable latch
 - Write-protect pin
- High Reliability:
 - Endurance: 1 Million erase/write cycles
 - Data Retention: >200 years
 - ESD Protection: >4000V
- Temperature Ranges Supported:
 - Industrial (I): -40°C to +85°C
 - Extended (E): -40°C to +125°C
- RoHS Compliant
- Automotive AEC-Q100 Qualified

Pin Function Table

Name	Function
$\overline{CS}$	Chip Select Input
SO	Serial Data Output
$\overline{WP}$	Write-Protect
Vss	Ground
SI	Serial Data Input
SCK	Serial Clock Input
$\overline{HOLD}$	Hold Input
Vcc	Supply Voltage

Description

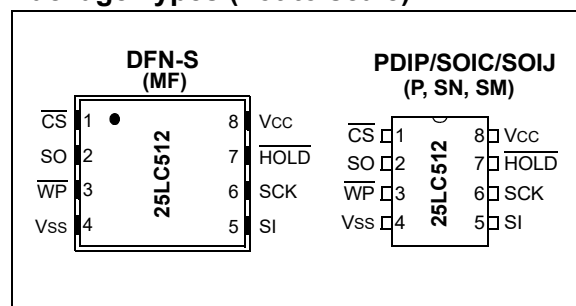
The Microchip Technology Inc. 25LC512 is a 512 Kbit serial EEPROM memory with byte-level and page-level serial EEPROM functions. It also features Page, Sector and Chip erase functions typically associated with Flash-based products. These functions are not required for byte or page write operations. The memory is accessed via a simple Serial Peripheral Interface (SPI) compatible serial bus. The bus signals required are a clock input (SCK) plus separate data in (SI) and data out (SO) lines. Access to the device is controlled by a Chip Select (CS) input.

Communication to the device can be paused via the hold pin ($\overline{HOLD}$). While the device is paused, transitions on its inputs will be ignored, with the exception of Chip Select, allowing the host to service higher priority interrupts.

Packages

- 8-Lead DFN-S, 8-Lead PDIP, 8-Lead SOIC and 8-Lead SOIJ

Package Types (not to scale)



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings (†)

V _{CC}	6.5V
All inputs and outputs w.r.t. V _{SS}	-0.6V to V _{CC} +1.0V
Storage temperature	-65°C to 150°C
Ambient temperature under bias.....	-40°C to 125°C
ESD protection on all pins.....	4 kV

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for an extended period of time may affect device reliability.

TABLE 1-1: DC CHARACTERISTICS

DC CHARACTERISTICS			Electrical Characteristics:			
			Industrial (I): TA = -40°C to +85°C		V _{CC} = 2.5V to 5.5V	
			Extended (E): TA = -40°C to +125°C		V _{CC} = 2.5V to 5.5V	
Param. No.	Sym.	Characteristic	Min.	Max.	Units	Test Conditions
D001	V _{IH1}	High-level input voltage	0.7 x V _{CC}	V _{CC} + 1	V	
D002	V _{IL1}	Low-level input voltage	-0.3	0.3 x V _{CC}	V	V _{CC} ≥ 2.7V
D003	V _{IL2}		-0.3	0.2 x V _{CC}	V	V _{CC} < 2.7V
D004	V _{OL}	Low-level output voltage	—	0.4	V	I _{OL} = 2.1 mA
D005	V _{OH}	High-level output voltage	V _{CC} - 0.2	—	V	I _{OH} = -400 μA
D006	I _{LI}	Input leakage current	—	±1	μA	$\overline{CS}$ = V _{CC} , V _{IN} = V _{SS} or V _{CC}
D007	I _{LO}	Output leakage current	—	±1	μA	$\overline{CS}$ = V _{CC} , V _{OUT} = V _{SS} or V _{CC}
D008	C _{INT}	Internal capacitance (all inputs and outputs)	—	7	pF	TA = 25°C, CLK = 1.0 MHz, V _{CC} = 5.0V (Note)
D009	I _{CC} Read	Operating current	—	10	mA	V _{CC} = 5.5V; F _{CLK} = 20.0 MHz; SO = Open
			—	5	mA	V _{CC} = 2.5V; F _{CLK} = 10.0 MHz; SO = Open
D010	I _{CC} Write		—	7	mA	V _{CC} = 5.5V
			—	5	mA	V _{CC} = 2.5V
D011	I _{CCS}	Standby current	—	20	μA	$\overline{CS}$ = V _{CC} = 5.5V, Inputs tied to V _{CC} or V _{SS} , 125°C
			—	10	μA	$\overline{CS}$ = V _{CC} = 5.5V, Inputs tied to V _{CC} or V _{SS} , 85°C
D012	I _{CCSPD}	Deep power-down current	—	2	μA	$\overline{CS}$ = V _{CC} = 2.5V, Inputs tied to V _{CC} or V _{SS} , 125°C
			—	1	μA	$\overline{CS}$ = V _{CC} = 2.5V, Inputs tied to V _{CC} or V _{SS} , 85°C

Note: This parameter is periodically sampled and not 100% tested.

TABLE 1-2: AC CHARACTERISTICS

AC CHARACTERISTICS			Electrical Characteristics:			
			Industrial (I):		TA = -40°C to +85°C	
			Extended (E):		TA = -40°C to +125°C	
					VCC = 2.5V to 5.5V	
					VCC = 2.5V to 5.5V	
Param. No.	Sym.	Characteristic	Min.	Max.	Units	Conditions
1	FCLK	Clock frequency	—	20	MHz	4.5V ≤ VCC ≤ 5.5V (I)
			—	10	MHz	2.5V ≤ VCC < 5.5V (I, E)
2	TCSS	$\overline{\text{CS}}$ setup time	25	—	ns	4.5V ≤ VCC ≤ 5.5V (I)
			50	—	ns	2.5V ≤ VCC < 5.5V (I, E)
3	TCSH	$\overline{\text{CS}}$ hold time	50	—	ns	4.5V ≤ VCC ≤ 5.5V (I)
			100	—	ns	2.5V ≤ VCC < 5.5V (I, E)
4	TCSD	$\overline{\text{CS}}$ disable time	50	—	ns	—
5	Tsu	Data setup time	5	—	ns	4.5V ≤ VCC ≤ 5.5V (I)
			10	—	ns	2.5V ≤ VCC < 5.5V (I, E)
6	THD	Data hold time	10	—	ns	4.5V ≤ VCC ≤ 5.5V (I)
			20	—	ns	2.5V ≤ VCC < 5.5V (I, E)
7	TR	CLK rise time	—	20	ns	(Note 1)
8	TF	CLK fall time	—	20	ns	(Note 1)
9	THI	Clock high time	25	—	ns	4.5V ≤ VCC ≤ 5.5V (I)
			50	—	ns	2.5V ≤ VCC < 5.5V (I, E)
10	TLO	Clock low time	25	—	ns	4.5V ≤ VCC ≤ 5.5V (I)
			50	—	ns	2.5V ≤ VCC < 5.5V (I, E)
11	TCLD	Clock delay time	50	—	ns	—
12	TCLE	Clock enable time	50	—	ns	—
13	TV	Output valid from clock low	—	25	ns	4.5V ≤ VCC ≤ 5.5V (I)
			—	50	ns	2.5V ≤ VCC < 5.5V (I, E)
14	THO	Output hold time	0	—	ns	(Note 1)
15	TDIS	Output disable time	—	25	ns	4.5V ≤ VCC ≤ 5.5V (I)
			—	50	ns	2.5V ≤ VCC < 5.5V (I, E)
16	THS	$\overline{\text{HOLD}}$ setup time	10	—	ns	4.5V ≤ VCC ≤ 5.5V (I)
			20	—	ns	2.5V ≤ VCC < 5.5V (I, E)
17	THH	$\overline{\text{HOLD}}$ hold time	10	—	ns	4.5V ≤ VCC ≤ 5.5V (I)
			20	—	ns	2.5V ≤ VCC < 5.5V (I, E)
18	THZ	$\overline{\text{HOLD}}$ low to output High-Z	—	15	ns	4.5V ≤ VCC ≤ 5.5V (I)
			—	30	ns	2.5V ≤ VCC < 5.5V (I, E)
						(Note 1)
19	THV	$\overline{\text{HOLD}}$ high to output valid	—	15	ns	4.5V ≤ VCC ≤ 5.5V (I)
			—	30	ns	2.5V ≤ VCC < 5.5V (I, E)
20	TREL	$\overline{\text{CS}}$ High to Standby mode	—	100	μs	—
21	TPD	$\overline{\text{CS}}$ High to Deep power-down	—	100	μs	—
22	TCE	Chip erase cycle time	—	10	ms	—
23	TSE	Sector erase cycle time	—	10	ms	—
24	TWC	Internal write cycle time	—	5	ms	Byte or Page mode and Page Erase
25	—	Endurance	1M	—	E/W Cycles	Page mode, 25°C, 5.5V (Note 2)

Note 1: This parameter is periodically sampled and not 100% tested.

2: This parameter is not tested but established by characterization and qualification.

TABLE 1-3: AC TEST CONDITIONS

AC Waveform:	
V _{LO} = 0.2V	—
V _{HI} = V _{CC} - 0.2V	(Note 1)
V _{HI} = 4.0V	(Note 2)
C _L = 30 pF	—
Timing Measurement Reference Level	
Input	0.5 V _{CC}
Output	0.5 V _{CC}

Note 1: For V_{CC} ≤ 4.0V**2:** For V_{CC} > 4.0V

FIGURE 1-1: HOLD TIMING

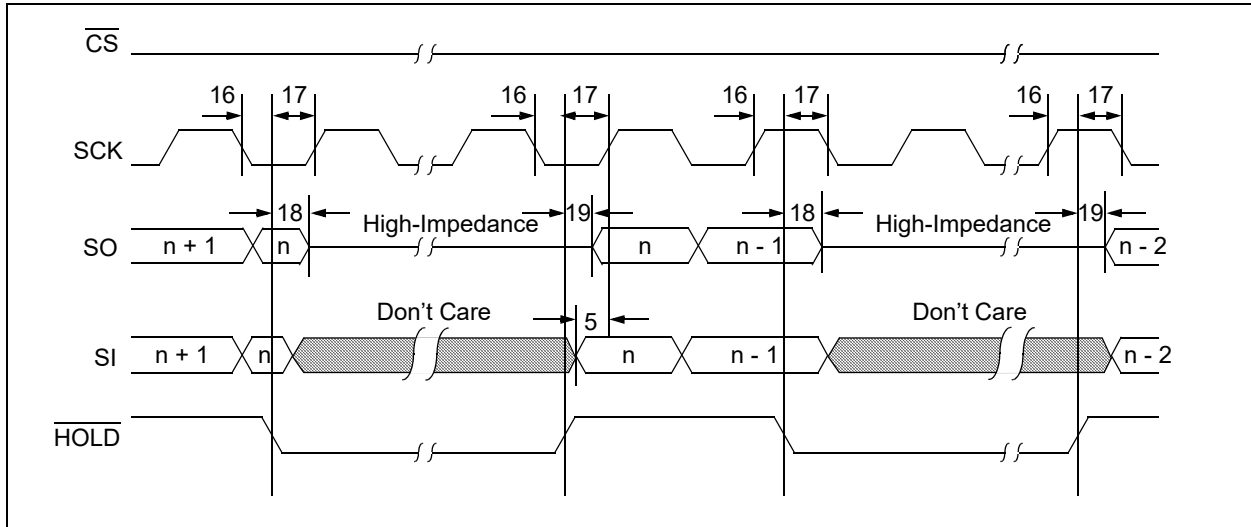


FIGURE 1-2: SERIAL INPUT TIMING

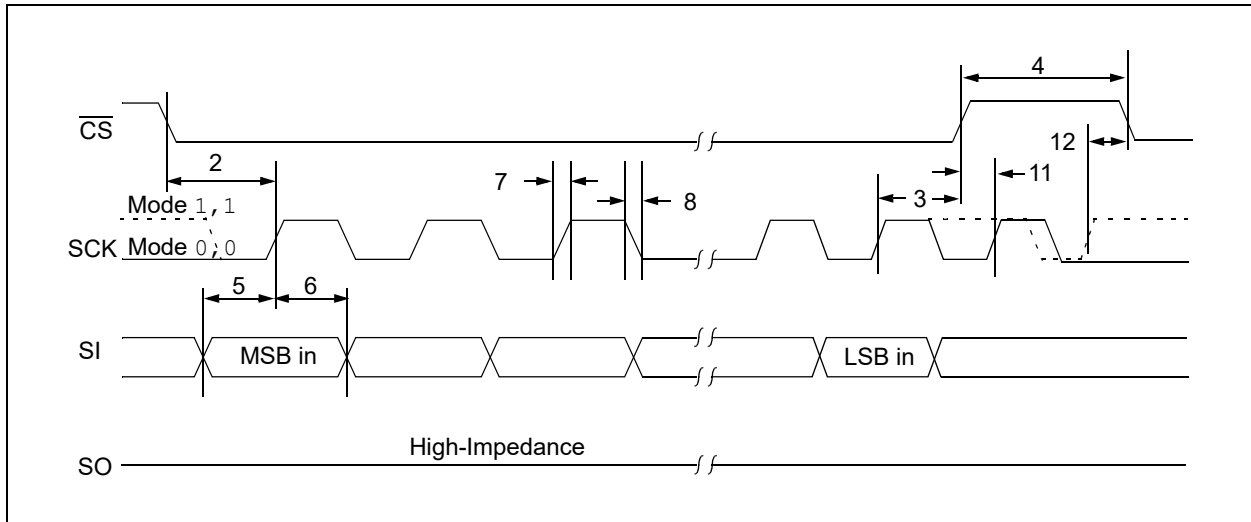
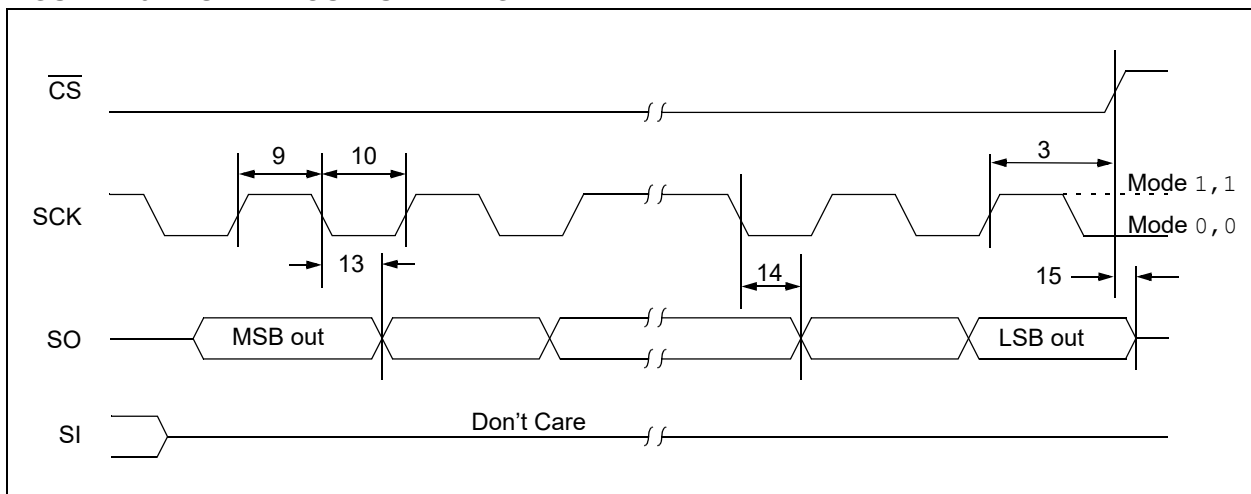


FIGURE 1-3: SERIAL OUTPUT TIMING



2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in [Table 2-1](#).

TABLE 2-1: PIN FUNCTION TABLE

Name	8-Lead DFN-S ⁽¹⁾	8-Lead PDIP	8-Lead SOIC	8-Lead SOIJ	Function
$\overline{\text{CS}}$	1	1	1	1	Chip Select Input
SO	2	2	2	2	Serial Data Output
$\overline{\text{WP}}$	3	3	3	3	Write-Protect Pin
Vss	4	4	4	4	Ground
SI	5	5	5	5	Serial Data Input
SCK	6	6	6	6	Serial Clock Input
$\overline{\text{HOLD}}$	7	7	7	7	Hold Input
Vcc	8	8	8	8	Supply Voltage

Note 1: The exposed pad on DFN-S package can be connected to Vss or left floating.

2.1 Chip Select ($\overline{\text{CS}}$)

A low level on this pin selects the device. A high level deselects the device and forces it into Standby mode. However, a programming cycle which is already initiated or in progress will be completed, regardless of the $\overline{\text{CS}}$ input signal. If $\overline{\text{CS}}$ is brought high during a program cycle, the device will go into Standby mode as soon as the programming cycle is complete. When the device is deselected, SO goes to the high-impedance state, allowing multiple parts to share the same SPI bus. A low-to-high transition on $\overline{\text{CS}}$ after a valid write sequence initiates an internal write cycle. After power-up, a low level on $\overline{\text{CS}}$ is required prior to any sequence being initiated.

2.2 Serial Output (SO)

The SO pin is used to transfer data out of the 25LC512. During a read cycle, data is shifted out on this pin after the falling edge of the serial clock.

2.3 Write-Protect ($\overline{\text{WP}}$)

This pin is used in conjunction with the WPEN bit in the STATUS register to prohibit writes to the nonvolatile bits in the STATUS register. When $\overline{\text{WP}}$ is low and WPEN is high, writing to the nonvolatile bits in the STATUS register is disabled. All other operations function normally. When $\overline{\text{WP}}$ is high, all functions, including writes to the nonvolatile bits in the STATUS register, operate normally. If the WPEN bit is set, $\overline{\text{WP}}$ low during a STATUS register write sequence will disable writing to the STATUS register. If an internal write cycle has already begun, $\overline{\text{WP}}$ going low will have no effect on the write.

The $\overline{\text{WP}}$ pin function is blocked when the WPEN bit in the STATUS register is low. This allows the user to install the 25LC512 in a system with $\overline{\text{WP}}$ pin grounded and still be able to write to the STATUS register. The $\overline{\text{WP}}$ pin functions will be enabled when the WPEN bit is set high.

2.4 Serial Input (SI)

The SI pin is used to transfer data into the device. It receives instructions, addresses and data. Data is latched on the rising edge of the serial clock.

2.5 Serial Clock (SCK)

The SCK is used to synchronize the communication between a host and the 25LC512. Instructions, addresses or data present on the SI pin are latched on the rising edge of the clock input, while data on the SO pin is updated after the falling edge of the clock input.

2.6 Hold ($\overline{\text{HOLD}}$)

The $\overline{\text{HOLD}}$ pin is used to suspend transmission to the 25LC512 while in the middle of a serial sequence without having to re-transmit the entire sequence over again. It must be held high any time this function is not being used. Once the device is selected and a serial sequence is underway, the $\overline{\text{HOLD}}$ pin may be pulled low to pause further serial communication without resetting the serial sequence.

The $\overline{\text{HOLD}}$ pin must be brought low while SCK is low, otherwise the $\overline{\text{HOLD}}$ function will not be invoked until the next SCK high-to-low transition. The 25LC512 must remain selected during this sequence. The SI and SCK levels are “don’t cares” during the time the device is paused and any transitions on these pins will be ignored. To resume serial communication, $\overline{\text{HOLD}}$

should be brought high while the SCK pin is low, otherwise serial communication will not be resumed until the next SCK high-to-low transition.

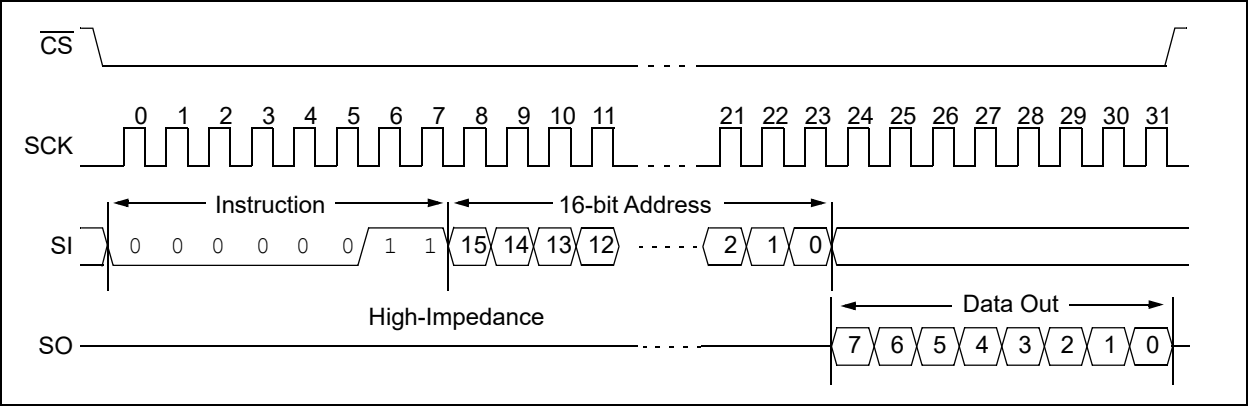
The SO line will tri-state immediately upon a high-to-low transition of the HOLD pin, and will begin outputting again immediately upon a subsequent low-to-high transition of the HOLD pin, independent of the state of SCK.

3.2 Read Sequence

The device is selected by pulling $\overline{\text{CS}}$ low. The 8-bit READ instruction is transmitted to the 25LC512 followed by the 16-bit address. After the correct READ instruction and address are sent, the data stored in the memory at the selected address is shifted out on the SO pin. The data stored in the memory at the next address can be read sequentially by continuing to

provide clock pulses. The internal Address Pointer is automatically incremented to the next higher address after each byte of data is shifted out. When the highest address is reached (FFFFh), the address counter rolls over to address 0000h allowing the read cycle to be continued indefinitely. The READ instruction is terminated by raising the $\overline{\text{CS}}$ pin (Figure 3-1).

FIGURE 3-1: READ SEQUENCE



3.3 Write Sequence

Prior to any attempt to write data to the 25LC512, the write enable latch must be set by issuing the `WREN` instruction (Figure 3-4). This is done by setting $\overline{CS}$ low and then clocking out the proper instruction into the 25LC512. After all eight bits of the instruction are transmitted, the $\overline{CS}$ must be brought high to set the write enable latch. If the write operation is initiated immediately after the `WREN` instruction without $\overline{CS}$ being brought high, the data will not be written to the array because the write enable latch will not have been properly set.

A write sequence includes an automatic, self timed erase cycle. It is not required to erase any portion of the memory prior to issuing a `WRITE` instruction.

Once the write enable latch is set, the user may proceed by setting the $\overline{CS}$ low, issuing a `WRITE` instruction, followed by the 16-bit address, and then the data to be written. Up to 128 bytes of data can be sent to the device before a write cycle is necessary. The only restriction is that all of the bytes must reside in the same page.

Note: When doing a write of less than 128 bytes the data in the rest of the page is refreshed along with the data bytes being written. This will force the entire page to endure a write cycle, for this reason endurance is specified per page.

Note: Page write operations are limited to writing bytes within a single physical page, **regardless** of the number of bytes actually being written. Physical page boundaries start at addresses that are integer multiples of the page buffer size (or 'page size'), and end at addresses that are integer multiples of page size - 1. If a Page Write command attempts to write across a physical page boundary, the result is that the data wraps around to the beginning of the current page (overwriting data previously stored there), instead of being written to the next page as might be expected. It is therefore necessary for the application software to prevent page write operations that would attempt to cross a page boundary.

For the data to be actually written to the array, the $\overline{CS}$ must be brought high after the Least Significant bit (D0) of the n^{th} data byte has been clocked in. If $\overline{CS}$ is brought high at any other time, the write operation will not be completed. Refer to Figure 3-2 and Figure 3-3 for more detailed illustrations on the byte write sequence and the page write sequence, respectively. While the write is in progress, the STATUS register may be read to check the status of the WPEN, WIP, WEL, BP1 and BP0 bits (Figure 3-6). A read attempt of a memory array location will not be possible during a write cycle. When the write cycle is completed, the write enable latch is reset.

FIGURE 3-2: BYTE WRITE SEQUENCE

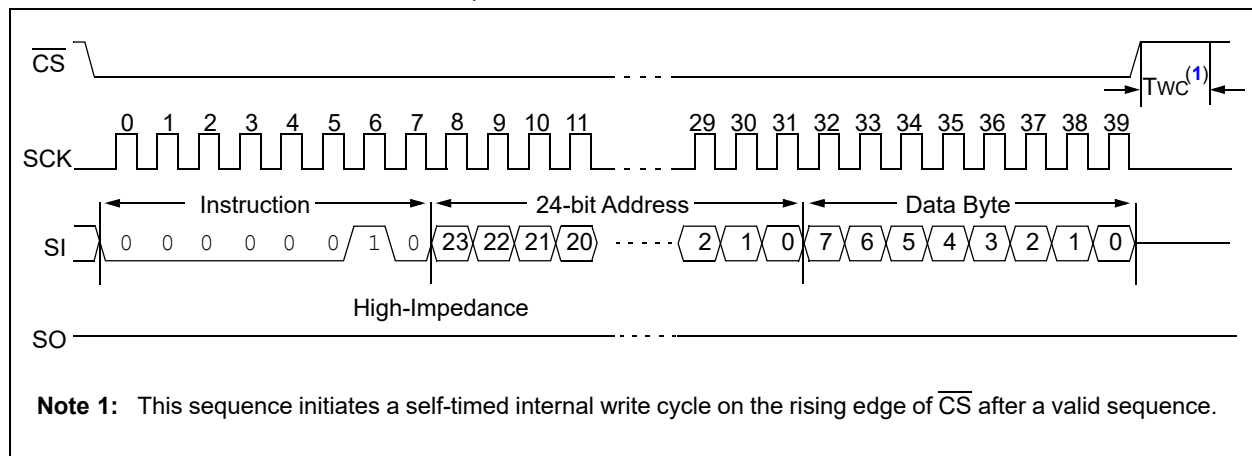
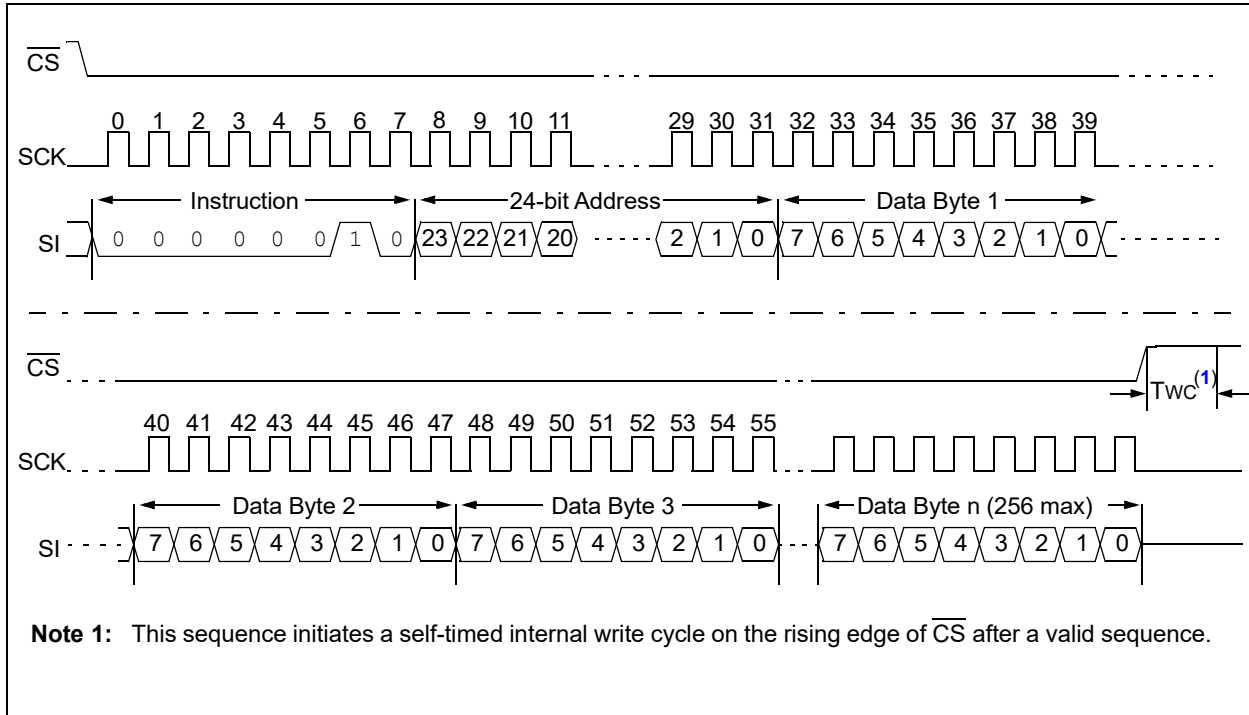


FIGURE 3-3: PAGE WRITE SEQUENCE



3.4 Write Enable (WREN) and Write Disable (WRDI)

The 25LC512 contains a write enable latch. See [Table 3-4](#) for the Write-Protect Functionality Matrix. This latch must be set before any write operation will be completed internally. The WREN instruction will set the latch, and the WRDI will reset the latch.

The following is a list of conditions under which the write enable latch will be reset:

- Power-up
- WRDI instruction successfully executed
- WRSR instruction successfully executed
- WRITE instruction successfully executed
- PE instruction successfully executed
- SE instruction successfully executed
- CE instruction successfully executed

FIGURE 3-4: WRITE ENABLE SEQUENCE (WREN)

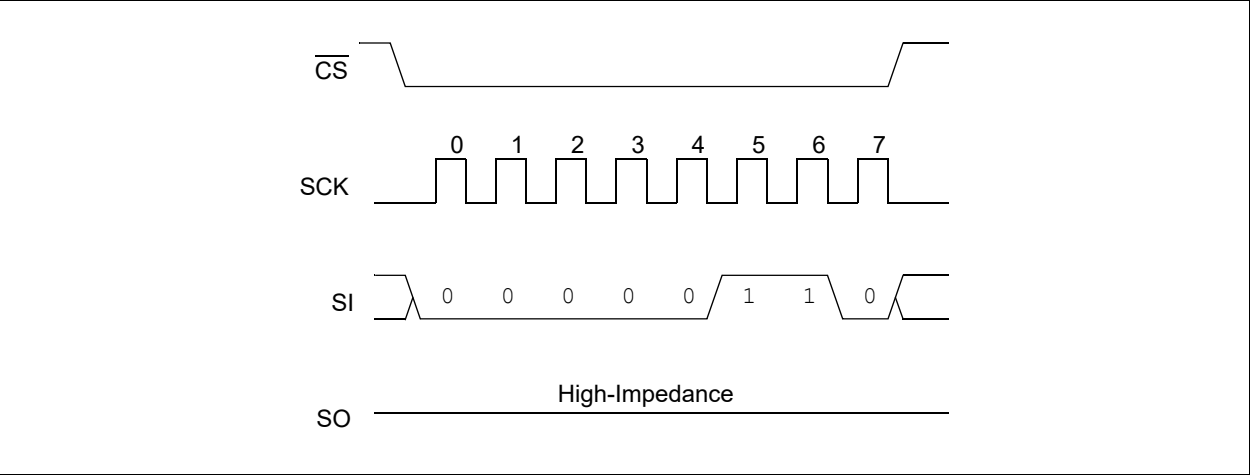
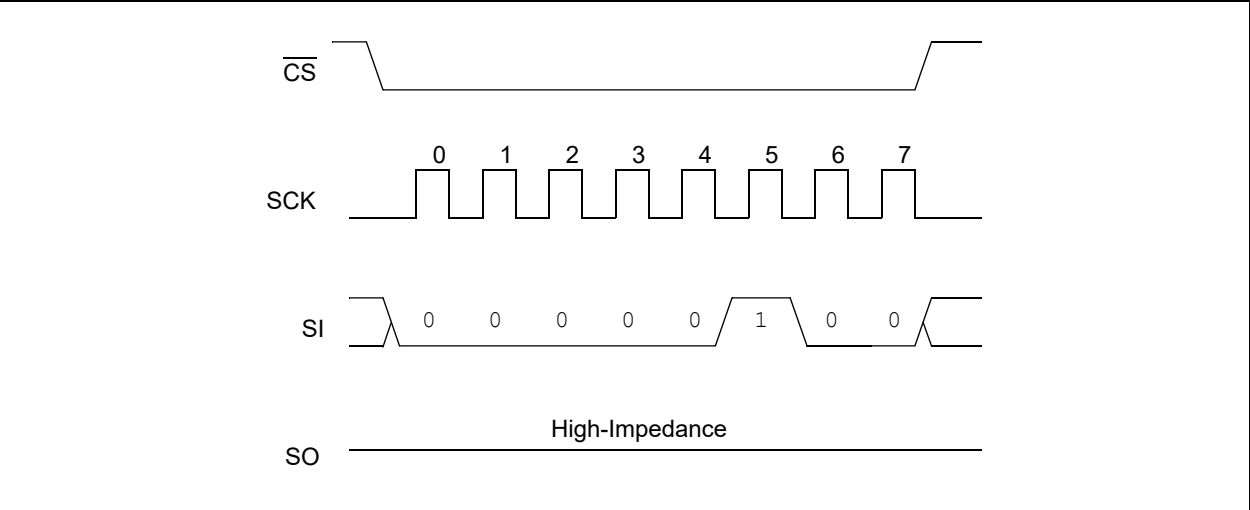


FIGURE 3-5: WRITE DISABLE SEQUENCE (WRDI)



3.5 Read Status Register Instruction (RDSR)

The Read Status Register instruction (RDSR) provides access to the STATUS register. The STATUS register may be read at any time, even during a write cycle. The STATUS register is formatted as follows:

TABLE 3-2: STATUS REGISTER

7	6	5	4	3	2	1	0
W/R	–	–	–	W/R	W/R	R	R
WPEN	X	X	X	BP1	BP0	WEL	WIP

Note: W/R = writable/readable. R = read-only.

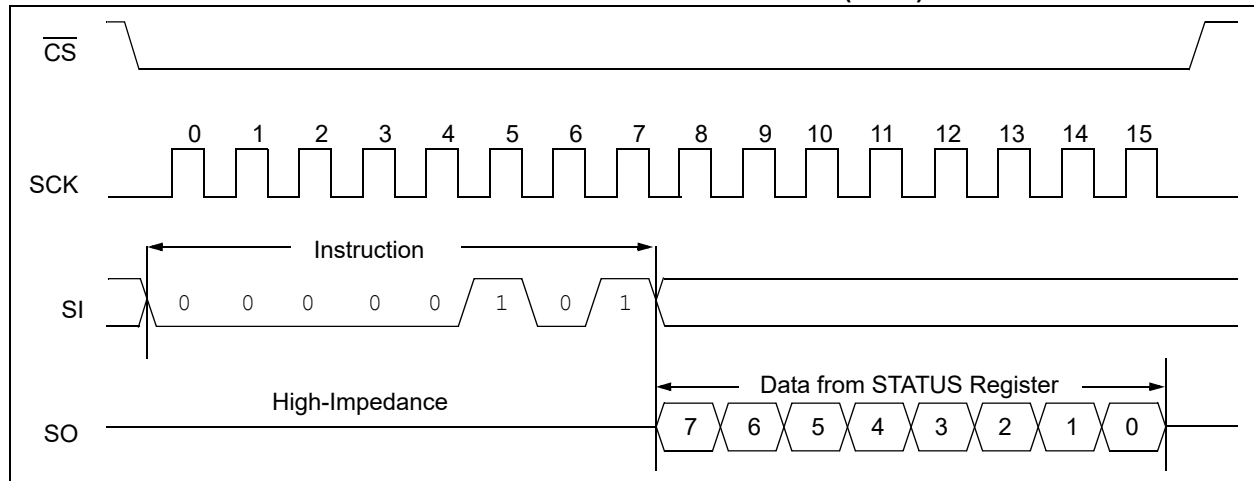
The **Write-In-Process (WIP)** bit indicates whether the 25LC512 is busy with a write operation. When set to a '1', a write is in progress, when set to a '0', no write is in progress. This bit is read-only.

The **Write Enable Latch (WEL)** bit indicates the status of the write enable latch and is read-only. When set to a '1', the latch allows writes to the array, when set to a '0', the latch prohibits writes to the array. The state of this bit can always be updated via the **WREN** or **WRDI** commands regardless of the state of write protection on the STATUS register. These commands are shown in [Figure 3-4](#) and [Figure 3-5](#).

The **Block Protection (BP0 and BP1)** bits indicate which blocks are currently write-protected. These bits are set by the user issuing the **WRSR** instruction. These bits are nonvolatile, and are shown in [Table 3-3](#).

See [Figure 3-6](#) for the RDSR timing sequence.

FIGURE 3-6: READ STATUS REGISTER TIMING SEQUENCE (RDSR)



3.6 Write Status Register Instruction (WRSR)

The Write Status Register instruction (WRSR) allows the user to write to the nonvolatile bits in the STATUS register as shown in Table 3-2. The user is able to select one of four levels of protection for the array by writing to the appropriate bits in the STATUS register. The array is divided up into four segments. The user has the ability to write-protect none, one, two or all four of the segments of the array. The partitioning is controlled as shown in Table 3-3.

The Write-Protect Enable (WPEN) bit is a nonvolatile bit that is available as an enable bit for the $\overline{\text{WP}}$ pin. The Write-Protect (WP) pin and the Write-Protect Enable (WPEN) bit in the STATUS register control the programmable hardware write-protect feature. Hardware write protection is enabled when WP pin is low and the WPEN bit is high. Hardware write protection is disabled when either the $\overline{\text{WP}}$ pin is high or the WPEN bit is low. When the chip is hardware write-protected, only writes to nonvolatile bits in the STATUS register are disabled. See Table 3-4 for a matrix of functionality on the WPEN bit. See Figure 3-7 for the WRSR timing sequence.

TABLE 3-3: ARRAY PROTECTION

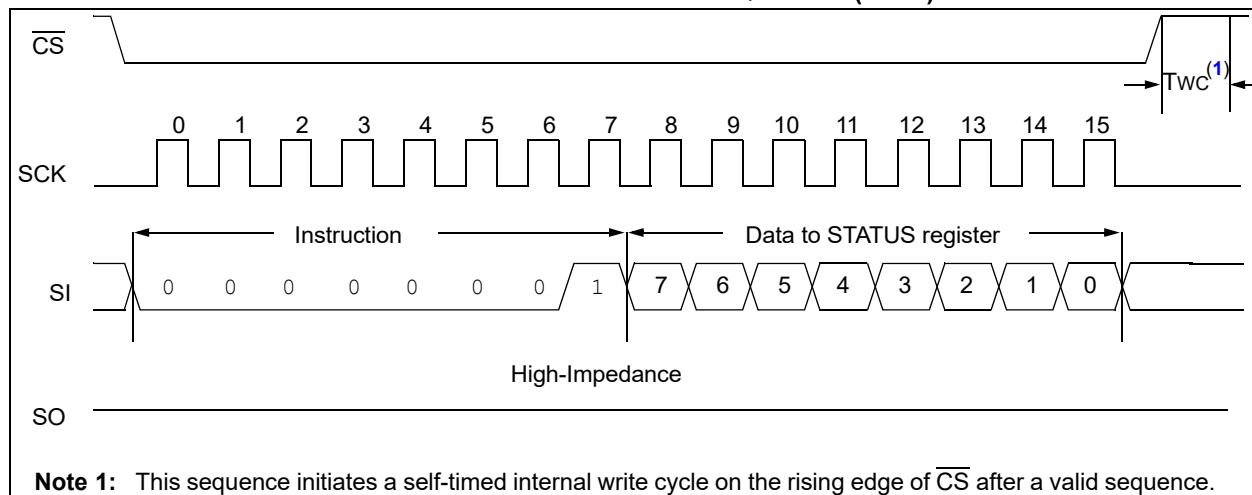
BP1	BP0	Array Addresses Write-Protected	Array Addresses Unprotected
0	0	none	All (Sectors 0, 1, 2 & 3) (0000h-FFFFh)
0	1	Upper 1/4 (Sector 3) (C000h-FFFFh)	Lower 3/4 (Sectors 0, 1 & 2) (0000h-BFFFh)
1	0	Upper 1/2 (Sectors 2 & 3) (8000h-FFFFh)	Lower 1/2 (Sectors 0 & 1) (0000h-7FFFh)
1	1	All (Sectors 0, 1, 2 & 3) (0000h-FFFFh)	none

TABLE 3-4: WRITE-PROTECT FUNCTIONALITY MATRIX

WEL (SR bit 1)	WPEN (SR bit 7)	$\overline{\text{WP}}$ (pin 3)	Protected Blocks	Unprotected Blocks	STATUS Register
0	x	x	Protected	Protected	Protected
1	0	x	Protected	Writable	Writable
1	1	0 (low)	Protected	Writable	Protected
1	1	1 (high)	Protected	Writable	Writable

x = don't care

FIGURE 3-7: WRITE STATUS REGISTER TIMING SEQUENCE (WRSR)



3.7 PAGE ERASE

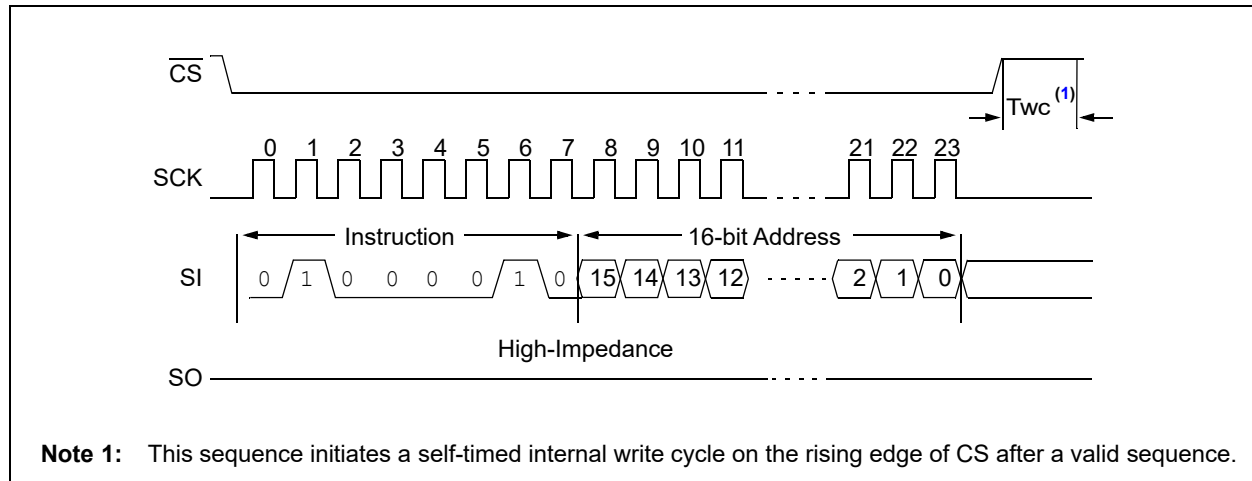
The `PAGE ERASE` instruction will erase all bits (FFh) inside the given page. A Write Enable (`WREN`) instruction must be given prior to attempting a `PAGE ERASE`. This is done by setting $\overline{CS}$ low and then clocking out the proper instruction into the 25LC512. After all eight bits of the instruction are transmitted, the $\overline{CS}$ must be brought high to set the write enable latch.

The `PAGE ERASE` instruction is entered by driving $\overline{CS}$ low, followed by the instruction code (Figure 3-8) and two address bytes. Any address inside the page to be erased is a valid address.

$\overline{CS}$ must then be driven high after the last bit of the address or the `PAGE ERASE` will not execute. Once the $\overline{CS}$ is driven high the self-timed `PAGE ERASE` cycle is started. The `WIP` bit in the `STATUS` register can be read to determine when the `PAGE ERASE` cycle is complete.

If a `PAGE ERASE` instruction is given to an address that has been protected by the Block Protect bits (`BP0`, `BP1`) then the sequence will be aborted and no erase will occur.

FIGURE 3-8: PAGE ERASE SEQUENCE



3.8 SECTOR ERASE

The SECTOR ERASE instruction will erase all bits (FFh) inside the given sector. A Write Enable (WREN) instruction must be given prior to attempting a SECTOR ERASE. This is done by setting $\overline{CS}$ low and then clocking out the proper instruction into the 25LC512. After all eight bits of the instruction are transmitted, the $\overline{CS}$ must be brought high to set the write enable latch.

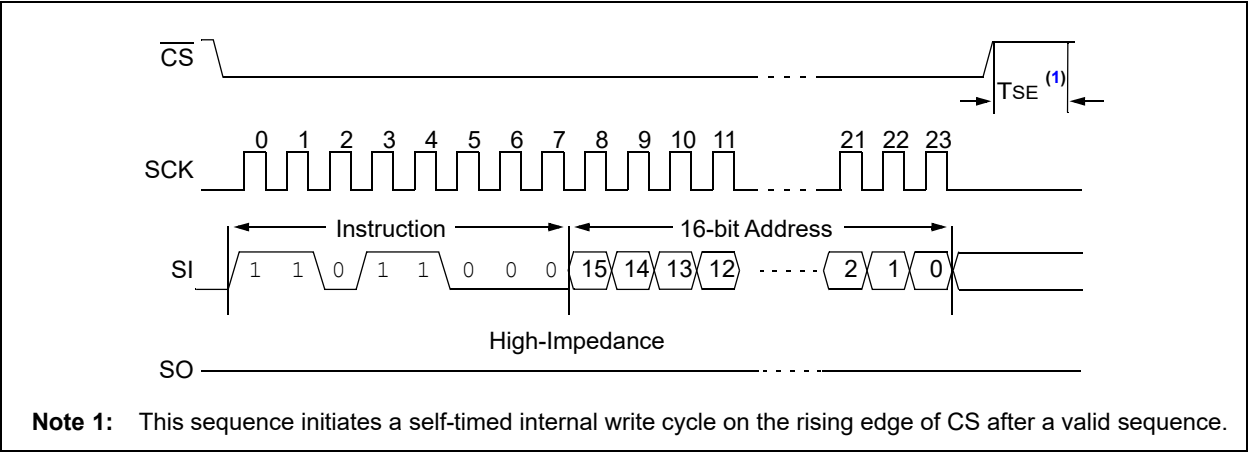
The SECTOR ERASE instruction is entered by driving $\overline{CS}$ low, followed by the instruction code (Figure 3-9) and two address bytes. Any address inside the sector to be erased is a valid address.

$\overline{CS}$ must then be driven high after the last bit of the address or the SECTOR ERASE will not execute. Once the $\overline{CS}$ is driven high the self-timed SECTOR ERASE cycle is started. The WIP bit in the STATUS register can be read to determine when the SECTOR ERASE cycle is complete.

If a SECTOR ERASE instruction is given to an address that has been protected by the Block Protect bits (BP0, BP1) then the sequence will be aborted and no erase will occur.

See Table 3-3 for Sector Addressing.

FIGURE 3-9: SECTOR ERASE SEQUENCE



3.9 CHIP ERASE

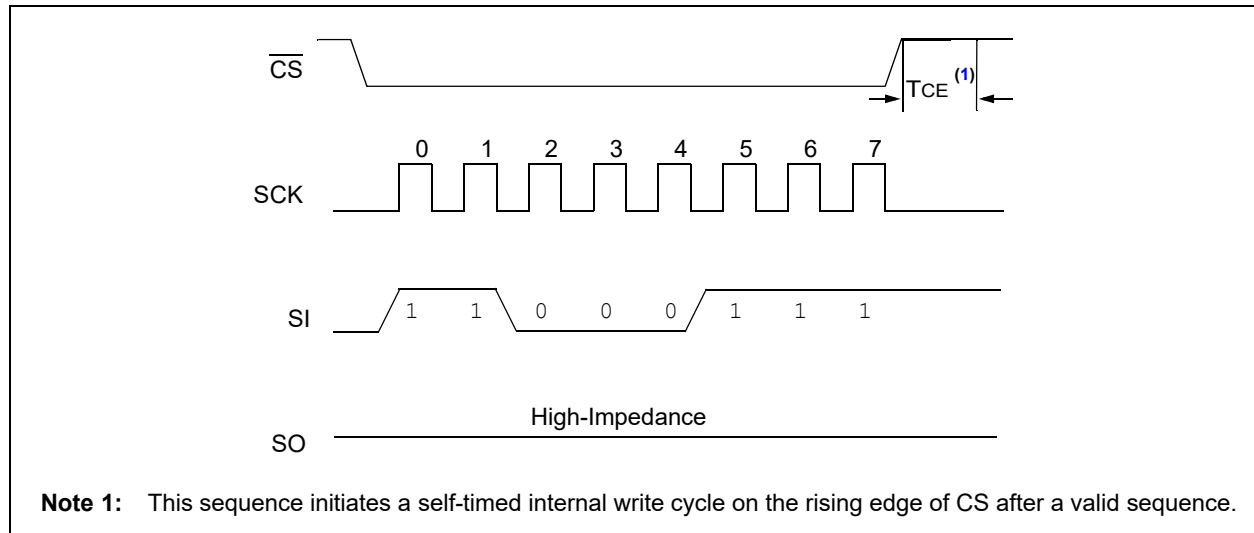
The `CHIP ERASE` instruction will erase all bits (FFh) in the array. A Write Enable (`WREN`) instruction must be given prior to executing a `CHIP ERASE`. This is done by setting $\overline{CS}$ low and then clocking out the proper instruction into the 25LC512. After all eight bits of the instruction are transmitted, the $\overline{CS}$ must be brought high to set the write enable latch.

The `CHIP ERASE` instruction is entered by driving the $\overline{CS}$ low, followed by the instruction code (Figure 3-10) onto the SI line.

The $\overline{CS}$ pin must be driven high after the eighth bit of the instruction code has been given or the `CHIP ERASE` instruction will not be executed. Once the $\overline{CS}$ pin is driven high the self-timed `CHIP ERASE` instruction begins. While the device is executing the `CHIP ERASE` instruction the `WIP` bit in the `STATUS` register can be read to determine when the `CHIP ERASE` instruction is complete.

The `CHIP ERASE` instruction is ignored if either of the Block Protect bits (`BP0`, `BP1`) are not 0, meaning $\frac{1}{4}$, $\frac{1}{2}$, or all of the array is protected.

FIGURE 3-10: CHIP ERASE SEQUENCE



3.10 DEEP POWER-DOWN MODE

Deep Power-Down mode of the 25LC512 is its lowest power consumption state. The device will not respond to any of the Read or Write commands while in Deep Power-Down mode, and therefore it can be used as an additional software write protection feature.

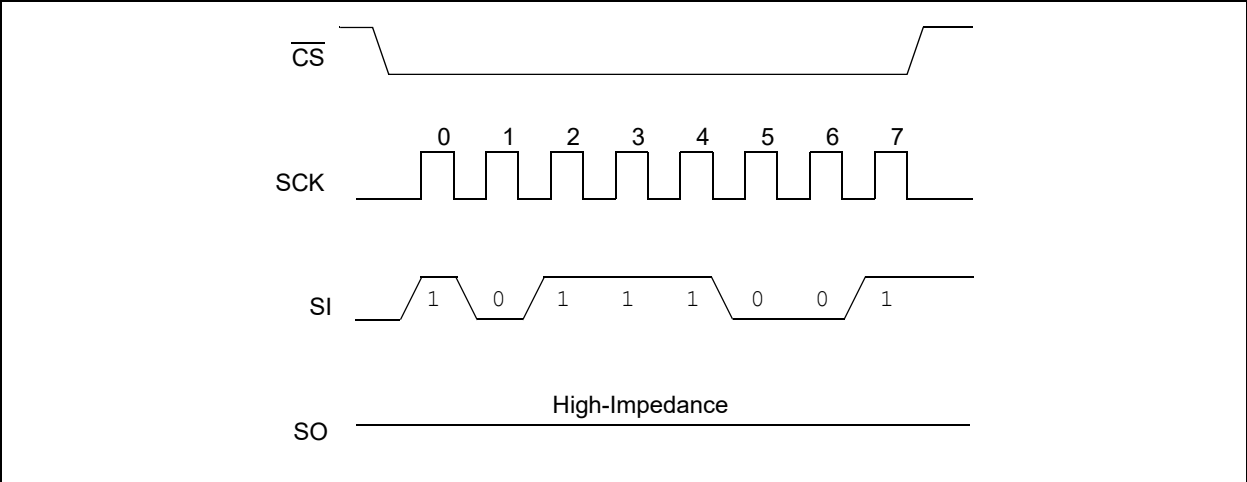
The Deep Power-Down mode is entered by driving $\overline{\text{CS}}$ low, followed by the instruction code (Figure 3-11) onto the SI line, followed by driving $\overline{\text{CS}}$ high.

If the $\overline{\text{CS}}$ pin is not driven high after the eighth bit of the instruction code has been given, the device will not execute Deep power-down. Once the $\overline{\text{CS}}$ line is driven high there is a delay (T_{DP}) before the current settles to its lowest consumption.

All instructions given during Deep Power-Down mode are ignored except the Read Electronic Signature command (RDID). The RDID command will release the device from Deep power-down and outputs the electronic signature on the SO pin, and then returns the device to Standby mode after delay (T_{REL})

Deep Power-Down mode automatically releases at device power-down. Once power is restored to the device it will power-up in the Standby mode.

FIGURE 3-11: DEEP POWER-DOWN SEQUENCE



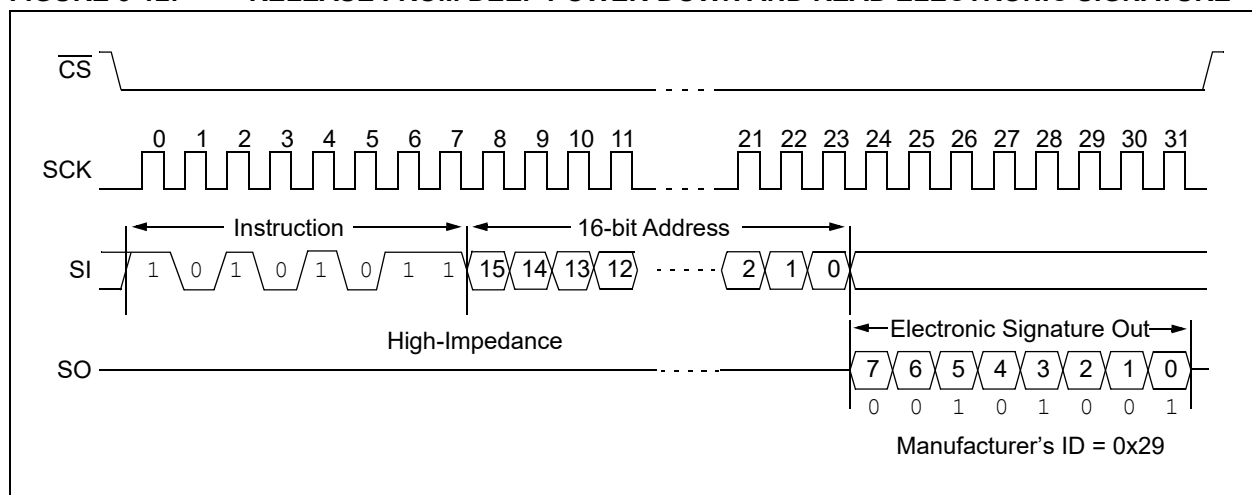
3.11 RELEASE FROM DEEP POWER-DOWN AND READ ELECTRONIC SIGNATURE

Once the device has entered Deep Power-Down mode all instructions are ignored except the Release from Deep Power-down and Read Electronic Signature command. This command can also be used when the device is not in Deep power-down to read the electronic signature out on the SO pin unless another command is being executed such as Erase, Program or Write Status Register.

Release from Deep Power-Down mode and Read Electronic Signature is entered by driving $\overline{CS}$ low, followed by the RDID instruction code (Figure 3-12) and then a dummy address of 16 bits (A15-A0). After the last bit of the dummy address is clock in, the 8-bit Electronic Signature is clocked out on the SO pin.

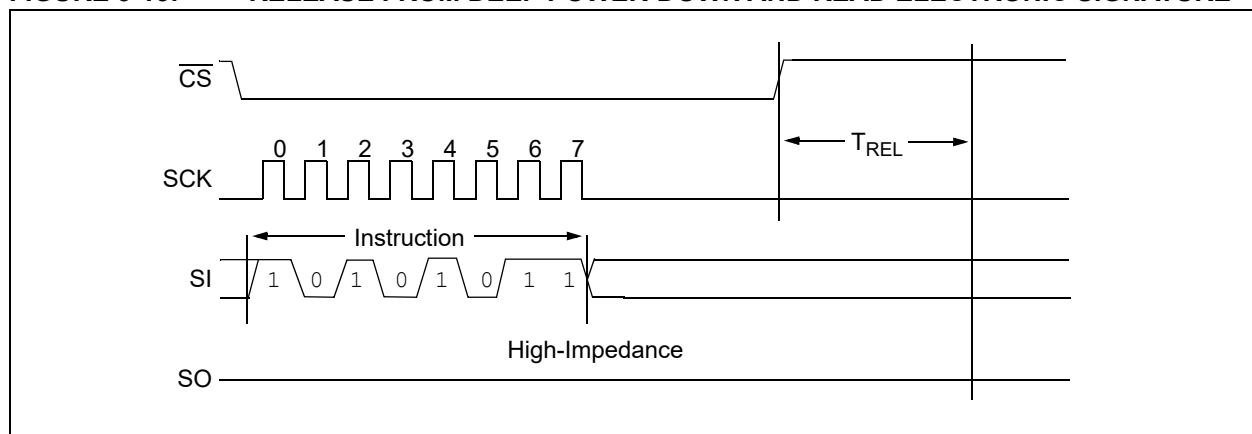
After the signature has been read out at least once, the sequence can be terminated by driving $\overline{CS}$ high. The device will then return to Standby mode and will wait to be selected so it can be given new instructions. If additional clock cycles are sent after the electronic signature has been read once, it will continue to output the signature on the SO line until the sequence is terminated.

FIGURE 3-12: RELEASE FROM DEEP POWER-DOWN AND READ ELECTRONIC SIGNATURE



Driving $\overline{CS}$ high after the 8-bit RDID command but before the Electronic Signature has been transmitted will still ensure the device will be taken out of Deep Power-Down mode. However, there is a delay T_{REL} that occurs before the device returns to Standby mode (I_{CCS}), as shown in Figure 3-13.

FIGURE 3-13: RELEASE FROM DEEP POWER-DOWN AND READ ELECTRONIC SIGNATURE



4.0 DATA PROTECTION

The following protection has been implemented to prevent inadvertent writes to the array:

- The write enable latch is reset on power-up
- A write enable instruction must be issued to set the write enable latch
- After a byte write, page write or STATUS register write, the write enable latch is reset
- $\overline{CS}$ must be set high after the proper number of clock cycles to start an internal write cycle
- Access to the array during an internal write cycle is ignored and programming is continued

5.0 POWER-ON STATE

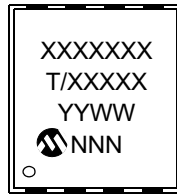
The 25LC512 powers on in the following state:

- The device is in low-power Standby mode ($\overline{CS} = 1$)
- The write enable latch is reset
- SO is in high-impedance state
- A high-to-low-level transition on $\overline{CS}$ is required to enter active state

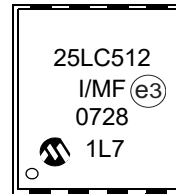
6.0 PACKAGING INFORMATION

6.1 Package Marking Information

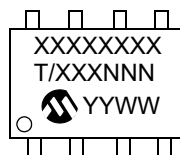
8-Lead DFN-S



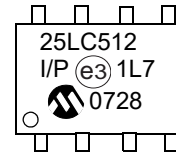
Example:



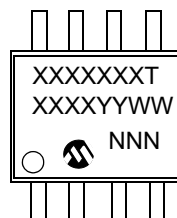
8-Lead PDIP



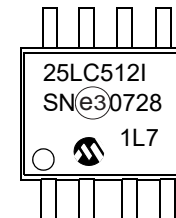
Example:



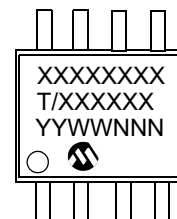
8-Lead SOIC



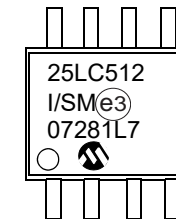
Example:



8-Lead SOIJ



Example:



1st Line Marking Codes

Device	DFN-S	PDIP	SOIC	SOIJ
25LC512	25LC512	25LC512	25LC512T	25LC512

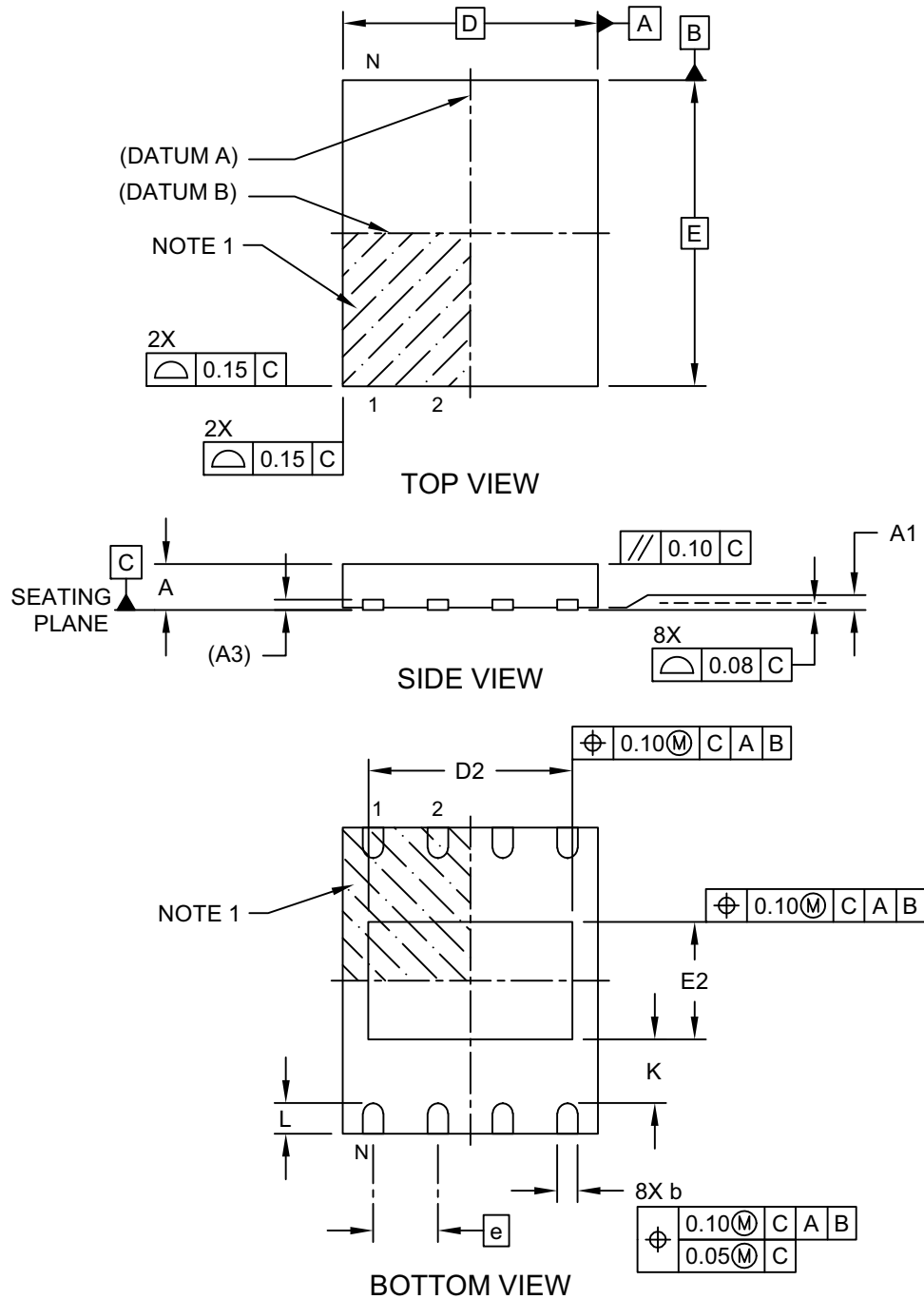
Legend: XX...X Part number or part number code
T Temperature (I, E)
Y Year code (last digit of calendar year)
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')
NNN Alphanumeric traceability code (2 characters for small packages)
e3 RoHS-compliant JEDEC designator for Matte Tin (Sn)

Note: For very small packages with no room for the RoHS-compliant JEDEC designator e3, the marking will only appear on the outer carton or reel label.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

8-Lead Plastic Dual Flat, No Lead Package (MF) - 6x5 mm Body [DFN-S] Saw Singulated

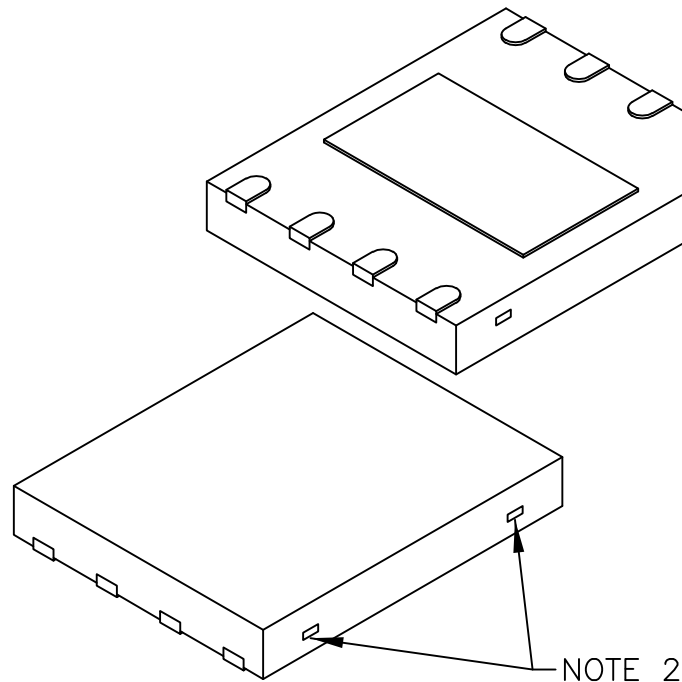
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-122 Rev C Sheet 1 of 2

8-Lead Plastic Dual Flat, No Lead Package (MF) - 6x5 mm Body [DFN-S] Saw Singulated

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	8		
Pitch	e	1.27 BSC		
Overall Height	A	0.80	0.85	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3	0.20 REF		
Overall Length	D	5.00 BSC		
Exposed Pad Length	D2	3.90	4.00	4.10
Overall Width	E	6.00 BSC		
Exposed Pad Width	E2	2.20	2.30	2.40
Terminal Width	b	0.30	0.40	0.50
Terminal Length	L	0.50	0.60	0.75
Terminal-to-Exposed-Pad	K	0.20	-	-

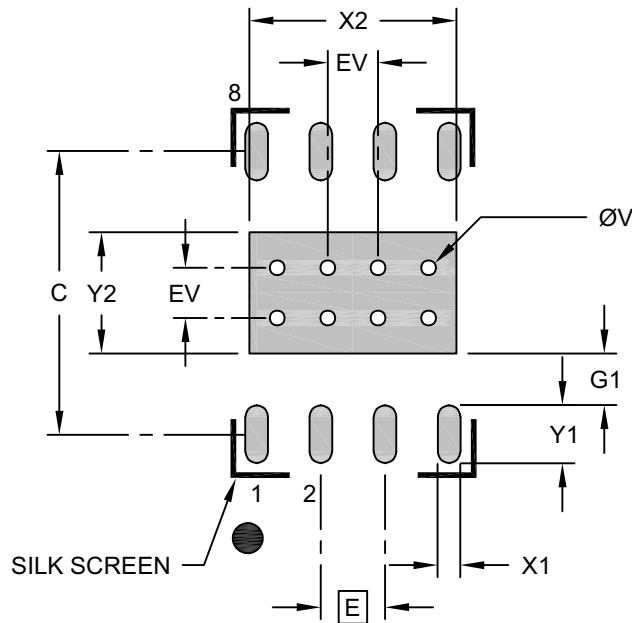
Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package may have one or more exposed tie bars at ends.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-122 Rev C Sheet 2 of 2

8-Lead Plastic Dual Flat, No Lead Package (MF) - 6x5 mm Body [DFN-S] Saw Singulated

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Optional Center Pad Width	X2			2.40
Optional Center Pad Length	Y2			4.10
Contact Pad Spacing	C		5.60	
Contact Pad Width (X20)	X1			0.45
Contact Pad Length (X20)	Y1			1.15
Contact Pad to Center Pad (X20)	G1	0.20		
Thermal Via Diameter	V		0.30	
Thermal Via Pitch	EV		1.00	

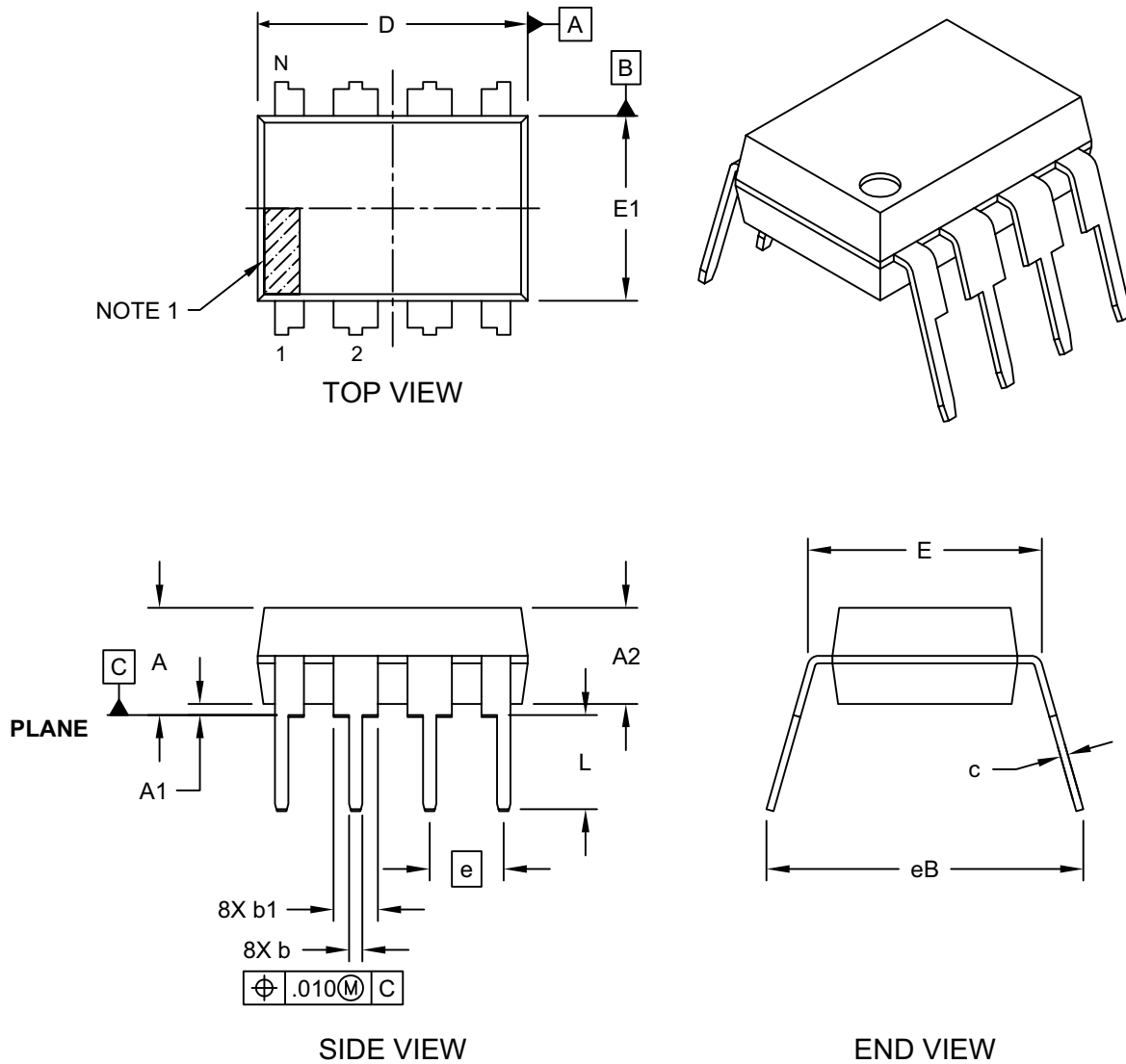
Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-2122 Rev C

8-Lead Plastic Dual In-Line (P) - 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

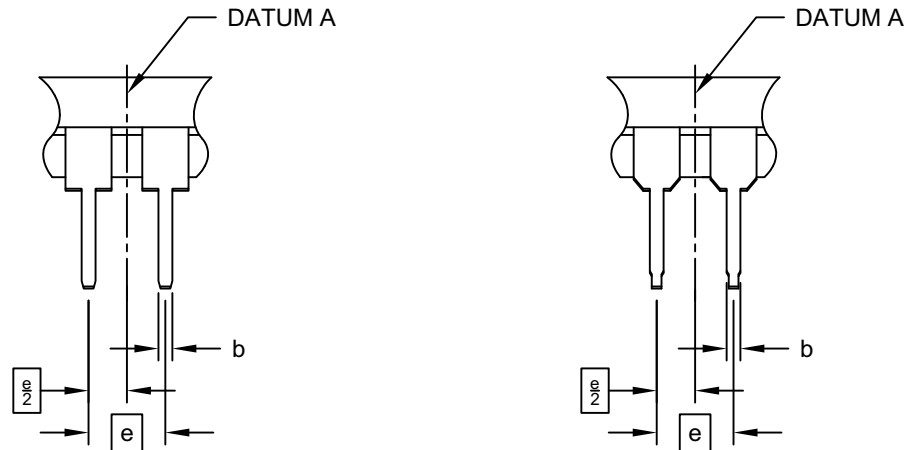


Microchip Technology Drawing No. C04-018-P Rev E Sheet 1 of 2

8-Lead Plastic Dual In-Line (P) - 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

ALTERNATE LEAD DESIGN (NOTE 5)



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	.100 BSC		
Top to Seating Plane	A	-	-	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	-	-
Shoulder to Shoulder Width	E	.290	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.348	.365	.400
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing	§	eB	-	.430

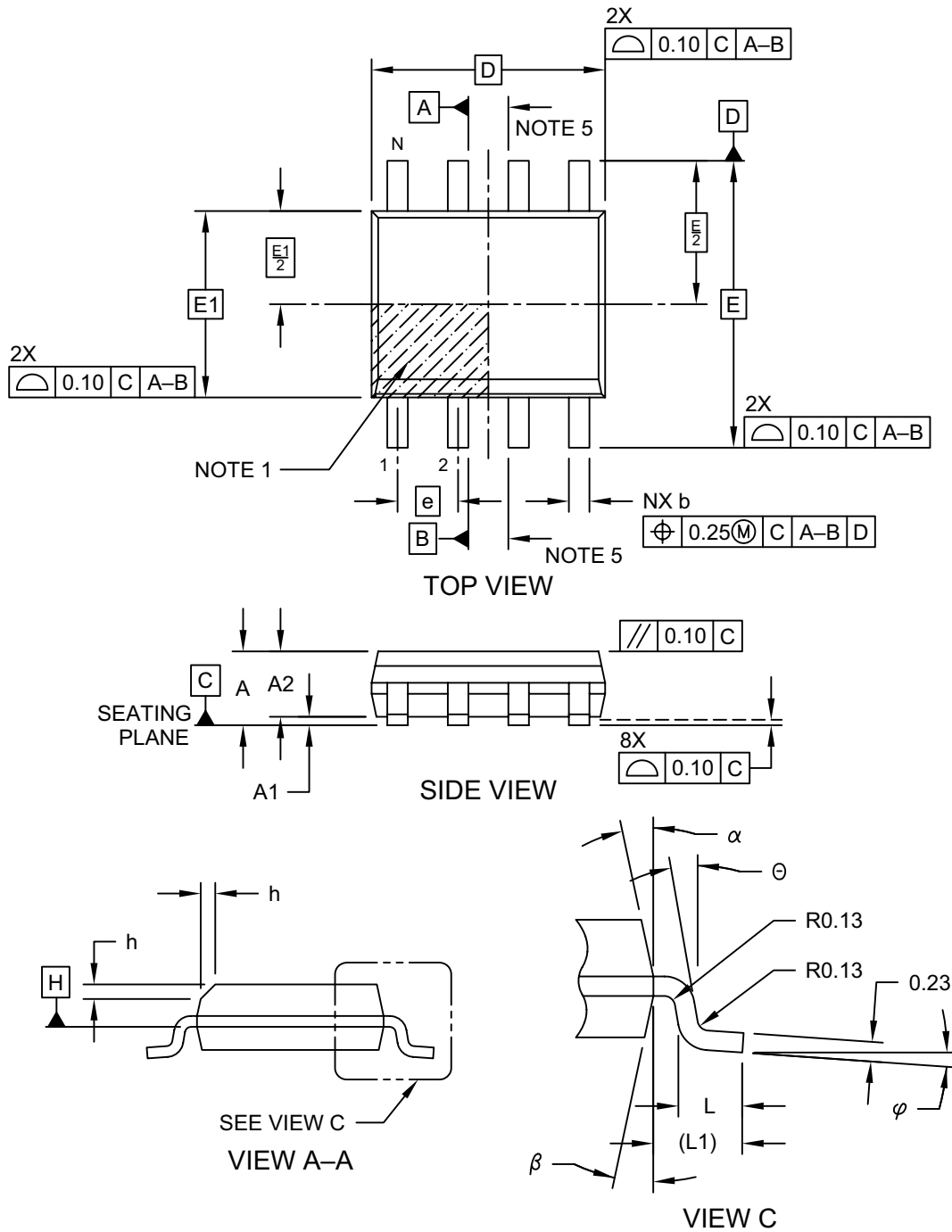
Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- Lead design above seating plane may vary, based on assembly vendor.

Microchip Technology Drawing No. C04-018-P Rev E Sheet 2 of 2

8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm (.150 In.) Body [SOIC]

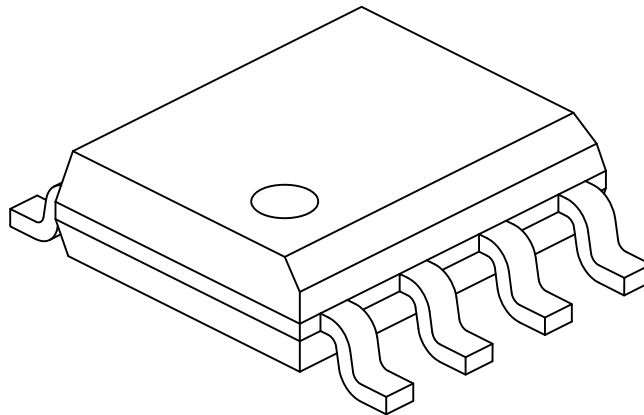
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing No. C04-057-SN Rev F Sheet 1 of 2

8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm (.150 In.) Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	1.27 BSC		
Overall Height	A	-	-	1.75
Molded Package Thickness	A2	1.25	-	-
Standoff §	A1	0.10	-	0.25
Overall Width	E	6.00 BSC		
Molded Package Width	E1	3.90 BSC		
Overall Length	D	4.90 BSC		
Chamfer (Optional)	h	0.25	-	0.50
Foot Length	L	0.40	-	1.27
Footprint	L1	1.04 REF		
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.17	-	0.25
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

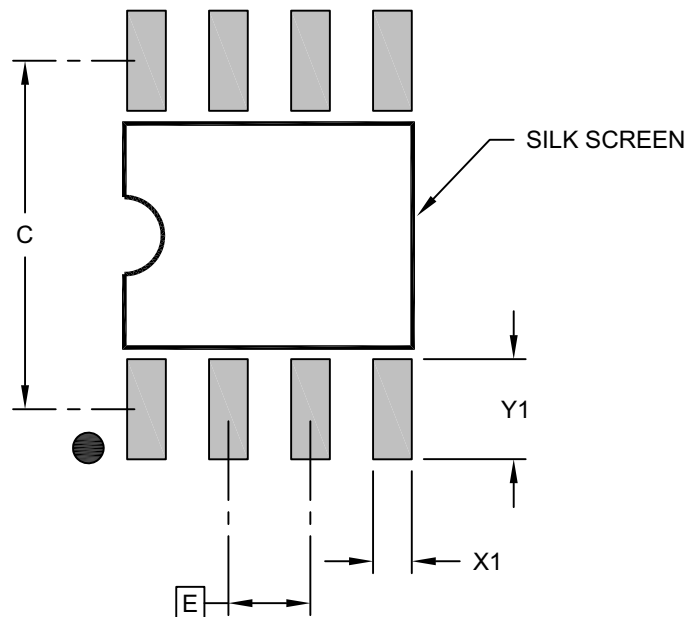
Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.
- Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-057-SN Rev F Sheet 2 of 2

8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm (.150 In.) Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		5.40	
Contact Pad Width (X8)	X1			0.60
Contact Pad Length (X8)	Y1			1.55

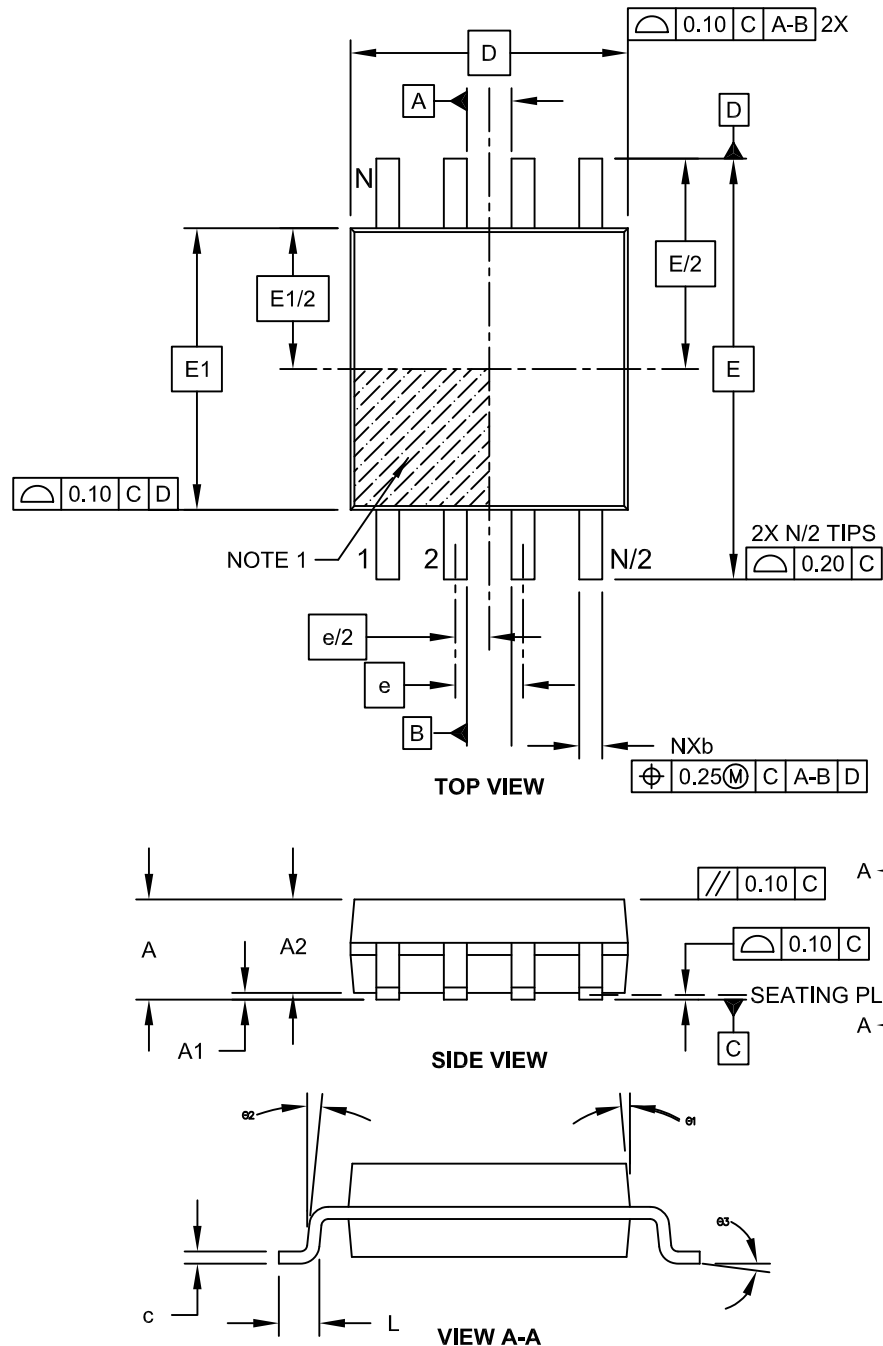
Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2057-SN Rev F

8-Lead Plastic Small Outline (SM) - Medium, 5.28 mm Body [SOIJ]

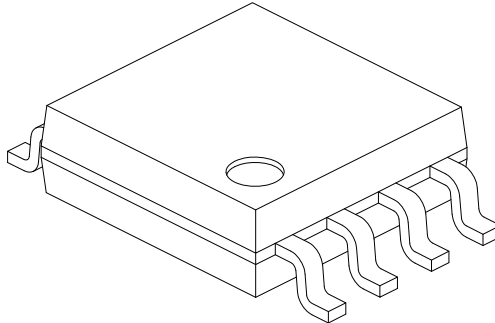
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-056C Sheet 1 of 2

8-Lead Plastic Small Outline (SM) - Medium, 5.28 mm Body [SOIJ]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	1.27 BSC		
Overall Height	A	1.77	-	2.03
Standoff §	A1	0.05		0.25
Molded Package Thickness	A2	1.75	-	1.98
Overall Width	E	7.94 BSC		
Molded Package Width	E1	5.25 BSC		
Overall Length	D	5.26 BSC		
Foot Length	L	0.51	-	0.76
Lead Thickness	c	0.15	-	0.25
Lead Width	b	0.36	-	0.51
Mold Draft Angle	Ø1	-	-	15°
Lead Angle	Ø2	0°	-	8°
Foot Angle	Ø3	0°	-	8°

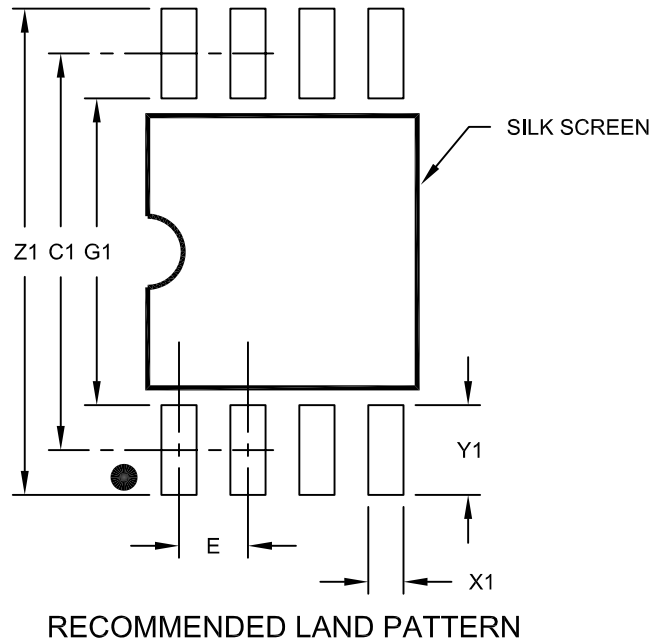
Notes:

1. SOIJ, JEITA/EIAJ Standard, Formerly called SOIC
2. § Significant Characteristic
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25mm per side.

Microchip Technology Drawing No. C04-056C Sheet 2 of 2

8-Lead Plastic Small Outline (SM) - Medium, 5.28 mm Body [SOIJ]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Overall Width	Z1			9.00
Contact Pad Spacing	C1		7.30	
Contact Pad Width (X8)	X1			0.65
Contact Pad Length (X8)	Y1			1.70
Distance Between Pads	G1	5.60		
Distance Between Pads	G	0.62		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2056C

APPENDIX A: REVISION HISTORY

Revision D (08/2021)

Updated Pin Description section; Updated Package Drawings; Added Product Identification System for Automotive; Replaced terminology “Master” and “Slave” with “Host” and “Client”, respectively; Reformatted some sections for better readability.

Revision C (05/2010)

Revised Table 1-2, Param. No. 25 Conditions; Revised Section 2.2, added note; Updated SOIJ package drawings.

Revision B (05/2008)

Modified parameter D006 in Table 1-1; Revised Package Marking Information; Replaced Package Drawings; Revised Product ID section.

Revision A (10/2007)

Original release.

NOTES:

THE MICROCHIP WEBSITE

Microchip provides online support via our WWW site at www.microchip.com. This website is used as a means to make files and information easily available to customers. Accessible by using your favorite Internet browser, the website contains the following information:

- **Product Support** – Data sheets and errata, application notes and sample programs, design resources, user's guides and hardware support documents, latest software releases and archived software
- **General Technical Support** – Frequently Asked Questions (FAQ), technical support requests, online discussion groups, Microchip consultant program member listing
- **Business of Microchip** – Product selector and ordering guides, latest Microchip press releases, listing of seminars and events, listings of Microchip sales offices, distributors and factory representatives

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- Distributor or Representative
- Local Sales Office
- Field Application Engineer (FAE)
- Technical Support

Customers should contact their distributor, representative or Field Application Engineer (FAE) for support. Local sales offices are also available to help customers. A listing of sales offices and locations is included in the back of this document.

Technical support is available through the website at: <http://microchip.com/support>

NOTES:

PRODUCT IDENTIFICATION SYSTEM (NON-AUTOMOTIVE)

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>		X ⁽¹⁾	-	X	/XX
Device	Tape & Reel	Temp Range	Package		
Device:	25LC512	512 Kbit, 2.5V, 128-Byte Page SPI Serial EEPROM			
Tape & Reel:	Blank	=	Standard packaging (tube)		
	T	=	Tape & Reel ⁽¹⁾		
Temperature Range:	I	=	-40°C to +85°C (Industrial)		
	E	=	-40°C to +125°C (Extended)		
Package:	MF	=	Plastic Dual Flat, No Lead Package		
			5 x 6 x 0.85 mm Body, 8-lead (DFN-S)		
	P	=	Plastic Dual In-Line - 300 mil Body, 8-lead (PDIP)		
	SN	=	Plastic Small Outline - Narrow, 3.90 mm Body, 8-lead (SOIC)		
	SM	=	Plastic Small Outline - Wide, 5.28 mm Body, 8-lead (SOIJ)		

Examples:

a) 25LC512-I/SM = 512 Kbit, 2.5V Serial EEPROM, Industrial temp., Tape and Reel, SOIC package

b) 25LC512-I/SM = 512 Kbit, 2.5V Serial EEPROM, Industrial temp., SOIJ package

c) 25LC512-I/P = 512 Kbit, 2.5V Serial EEPROM, Industrial temp., PDIP package

d) 25LC512T-E/MF = 512 Kbit, 2.5V Serial EEPROM, Extended temp., Tape and Reel, DFN-S package

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

25LC512

PRODUCT IDENTIFICATION SYSTEM (AUTOMOTIVE)

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.			X ⁽¹⁾	–	X	/XX	XXX ^(2,3)
Device			Tape & Reel		Temp Range	Package	Variant
Device:			25LC512		512 Kbit, 2.5V, 128-Byte Page SPI Serial EEPROM		
Tape & Reel:			Blank	=	Standard packaging (tube)		
			T	=	Tape & Reel ⁽¹⁾		
Temperature Range:			I	=	-40°C to +85°C (AEC-Q100 Grade 3)		
			E	=	-40°C to +125°C (AEC-Q100 Grade 1)		
Package:			SN	=	Plastic Small Outline - Narrow, 3.90 mm Body, 8-lead (SOIC)		
			SM	=	Plastic Small Outline - Wide, 5.28 mm Body, 8-lead (SOIJ)		
Variant^(2,3):			16KVAO=		Standard Automotive, 16K Process		
			16KVXX=		Customer-Specific Automotive, 16K Process		

Examples:

- a) 25LC512-I/SN16KVAO = 512 Kbit, 2.5V Serial EEPROM, Automotive Grade 3, SOIC package
- b) 25LC512T-I/SN16KVAO = 512 Kbit, 2.5V Serial EEPROM, Automotive Grade 3, Tape and Reel, SOIC package
- c) 25LC512-E/SN16KVAO = 512 Kbit, 2.5V Serial EEPROM, Automotive Grade 1, SOIC package
- d) 25LC512T-E/SN16KVAO = 512 Kbit, 2.5V Serial EEPROM, Automotive Grade 1, Tape and Reel, SOIC package
- e) 25LC512-E/SM16KVAO = 512 Kbit, 2.5V Serial EEPROM, Automotive Grade 1, SOIJ package
- f) 25LC512T-E/SM16KVAO = 512 Kbit, 2.5V Serial EEPROM, Automotive Grade 1, Tape and Reel, SOIJ package

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.
2: The VAO/VXX automotive variants have been designed, manufactured, tested and qualified in accordance with AEC-Q100 requirements for automotive applications.
3: For customers requesting a PPAP, a customer-specific part number will be generated and provided. A PPAP is not provided for VAO part numbers.

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